



## **ISC Audits & Reviews SC Summary (August 2017)**

<b>Doc.</b>	<b>Title</b>	<b>Results</b>
5596A;	New Standard: Guide To Assess and Minimize Electromagnetic Interference (EMI) in a Semiconductor Manufacturing Environment ;	Passed
5642A;	Revision to SEMI C35-0708, Specifications and Guideline for Nitric Acid with title change to: Specification and Guide for Nitric Acid;	Passed
5716;	Revisions to SEMI E133, Specification for Automated Process Control Systems Interface and SEMI E133.1, Provisional Specification for XML Messaging for Process Control Systems (PCS);	Passed
5822A;	New Standard, Specification for Reference Material for Bonded Wafer Stack Void Metrology;	Passed
5831B;	Revision to SEMI C27-0708, Specifications and Guideline for Hydrochloric Acid with title change to: Specification and Guide for Hydrochloric Acid;	Passed
5872C-LI1;	Enhancement to E172 ;	Passed
5915-LI1;	To add figures to newly provided Related Information 4 of M1 to illustrate the flatness metrics for silicon wafers and to add Table A1-1 to Appendix 1 with references for the figures added.;	Passed
5917A-LI1;	Revisions and additions to hand/arm clearances;	Passed
5917A-LI2;	Add a new Related Information section “Z” to assist with determining what tasks are within the scope of an assessment to SEMI S8;	Passed
5979;	New Standard: Specification of indoor lighting simulator requirements for emerging PV;	Passed
6019A-LI1;	Change ¶R3-4.4 as follows to point out that minority carrier lifetime measurements in electronic silicon manufacture must be controlled by recombination at impurities;	Passed
6041-LI1;	Changes to various related sections shown;	Passed
6042A-LI1;	Correct title and concomitant text.;	Passed
6056B;	Revision to SEMI E28-1110, Guide for Pressure Specifications of the Mass Flow Controller with Title Change to Guide for Pressure Parameters of the Mass Flow Controller;	Passed
6061;	Reapproval of SEMI M12-0706 (Reapproved 1011): Specification for Serial Alphanumeric Marking of the Front Surface of Wafers;	Passed
6062;	Reapproval of SEMI M13-0706 (Reapproved 1011): Specification for Alphanumeric Marking of Silicon Wafers;	Passed
6100;	Reapproval of SEMI PV1-0211 - Test Method for Measuring Trace Elements in Silicon Feedstock for Silicon Solar Cells by High-Mass Resolution Glow Discharge Mass Spectrometry;	Passed
6148-LI1;	Change nonconforming title;	Passed
6148-LI2;	Change section titles to meet the requirement which is specified section 3.2 of Procedure Manual;	Passed
6149-LI1;	Change section titles to meet the requirement which is specified section 3.2 of	Passed

Doc.	Title	Results
	Procedure Manual;	
6149-LI2;	Add "Calculation" section title and get re-formatted to meet the requirement which is specified section 3.2 of Procedure Manual;	Passed
6150-LI1;	Re-format some parts as to meet the requirement which is specified section 3.2 of Procedure Manual. ;	Passed
6151-LI1;	Re-format some parts as to meet the requirement which is specified section 3.2 of Procedure Manual. ;	Passed
6153;	Reapproval of SEMI G90-0811: Specification for 300 mm Wafer Coin-Stack Type Shipping Container Used for Test and Packaging Processes;	Passed
6155-LI1;	Re-format some parts as to meet the requirement which is specified section 3.2 of Procedure Manual. ;	Passed
6157;	Reapproval of SEMI G23-0996 (Reapproved 0811): Test Method of Inductance for Internal Traces of Semiconductor Packages;	Passed
6158;	Reapproval of SEMI G42-0996 (Reapproved 0811): Specification for Thermal Test Board Standardization for Measuring Junction-to-Ambient Thermal Resistance of Semiconductor Packages;	Passed
6159;	Reapproval of SEMI G59-94 (Reapproved 0811): Test Method for Measurement of Ionic Contamination on Leadframe Interleafing and the Contamination Transferred from the Interleafing to the Leadframes;	Passed
6160;	Reapproval of SEMI G60-94 (Reapproved 0811): Test Method for the Measurement of Electrostatic Properties of Semiconductor Leadframe Interleafing Materials;	Passed
6161;	Reapproval of SEMI G66-96 (Reapproved 0811): Test Method for the Measurement of Water Absorption Characteristics for Semiconductor Plastic Molding Compounds;	Passed
6162;	Reapproval of SEMI G67-0996 (Reapproved 0811): Test Method for the Measurement of Particle Generation from Sheet Materials;	Passed
6163;	Reapproval of SEMI G68-0996 (Reapproved 0811): Test Method for Junction-to-Case Thermal Resistance Measurements in Air Environment for Semiconductor Packages;	Passed
6164;	Reapproval of SEMI G69-0996 (Reapproved 0811): Test Method for Measurement of Adhesive Strength Between Leadframes and Molding Compounds ;	Passed
6165;	Reapproval of SEMI G71-0996 (Reapproved 0811): Specification for Barcode Marking of Intermediate Containers for Packaging Materials;	Passed
6166;	Reapproval of SEMI G89-0211: Specification for Leadframe Strip Size;	Passed
6169-LI1;	Delete Note 3 in section 2.5 and MF657 in section 4.1;	Passed
6169-LI2;	Delete Note 2 and Modify sections as shown;	Passed
6172-LI1;	Correct title and concomitant texts for S14;	Failed
6173-LI1;	Correct SEMI C30 nonconforming title per SEMI Standards Procedure Manual, from "Specifications for hydrogen Peroxide" to "Specification for Hydrogen Peroxide".;	Passed
6176;	Reapproval of SEMI MS1-0307 (Reapproved 0812), Guide to Specifying Wafer-Wafer Bonding Alignment Target;	Passed



Doc.	Title	Results
6177;	Reapproval of SEMI MS10-0912, Test Method to Measure Fluid Permeation Through MEMS Packaging Materials;	Passed
6178-LI1;	Correct nonconforming title per SEMI Standards Procedure Manual to "Test Method for Determination of Surface Roughness Parameters for Gas Distribution System Components";	Passed
6179;	Reapproval of SEMI 3D1-0912, Terminology for Through Silicon via Geometrical Metrology;	Passed
6180;	Reapproval of SEMI F64-0701 (Reapproved 1111), Test Method for Determining Pressure Effects on Indicated and Actual Flow for Mass Flow Controllers ;	Passed
6181;	Reapproval of SEMI F76-0303 (Reapproved 1110), Test Method for Evaluation of Particle Contribution from Gas System Components Exposed to Corrosive Gas;	Passed
6182;	Reapproval of SEMI C9.1-0212, Guide for Analysis of Uncertainties in Gravimetrically Prepared Gas Mixtures;	Passed
6183;	Reapproval of SEMI E82-1106 (Reapproved 0612), Specification for Interbay/Intrabay AMHS SEM (IBSEM) ;	Passed
6186;	Reapproval of SEMI C3.58-1011, Specification for Octafluorocyclobutane, C4F8, Electronic Grade in Cylinders, 99.999% Quality;	Passed
6187;	Reapproval of SEMI E88-0307 (Reapproved 0612), Specification for AMHS Storage SEM (Stocker SEM);	Passed
6188;	Reapproval of SEMI F54-1000 (Reapproved 1110), Test Method for Measuring the Counting Efficiency of Condensation Nucleus Counters;	Passed
R5634D;	Ratification Ballot: New Standard, Test Method for Color Reproduction and Perceptual Contrast of Displays;	Passed
R6089;	Ratification Ballot: Line Item Revision to "SEMI E170.1-0416: Specification For SECS-II Protocol For Secured Foundation Of Recipe Management System", "SEMI E170-0416: Specification For Secured Foundation Of Recipe Management System (SFORMS)" and "SEMI E5-0813: Semi Equipment Communications Standard 2 Message Content (SECS-II)" with title change;	Passed
	Editorial Changes to SEMI E137-0705 (Reapproved 1111) - Guide for Final Assembly, Packaging, Transportation, Unpacking, and Relocation of Semiconductor Manufacturing Equipment;	Passed
	Editorial Changes to E158, E159, E154;	Passed

Line Item (LI)

Doc. 6172 failed. All other documents passed and will be forwarded to Standards Publications for final processing.

For more information, please contact the SEMI Standards Engineer/Coordinator. (<http://www.semi.org/standards/contacts>) nearest you.

KN  
VI  
August 18, 2017